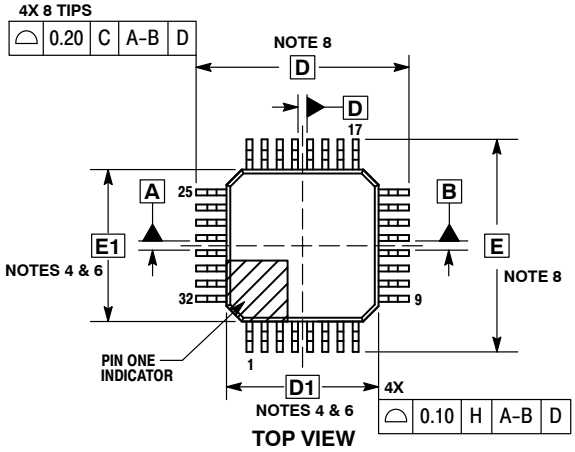
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

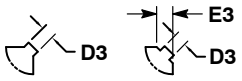
TQFP32 EP, 5x5
CASE 136AB
ISSUE B

DATE 28 JUN 2016

SCALE 1:1

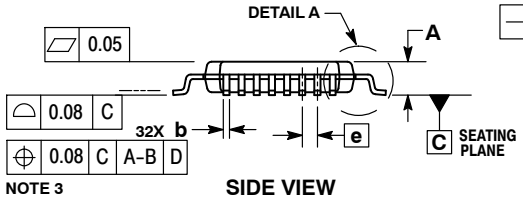


TOP VIEW

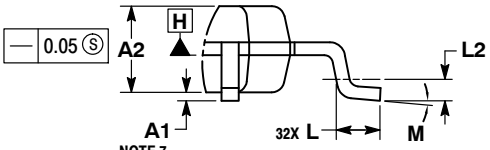


DETAIL B
ALTERNATE CONSTRUCTIONS

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY AS MUCH AS 0.15.
6. DATUMS A–B AND D ARE DETERMINED AT DATUM PLANE H.
7. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.

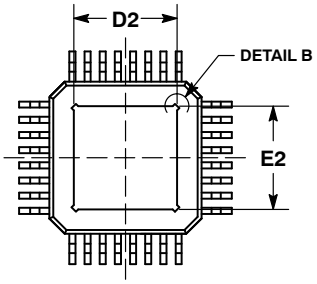


SIDE VIEW



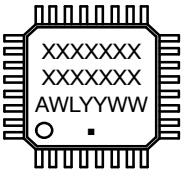
DETAIL A

DIM	MILLIMETERS MIN	MAX
A	---	1.20
A1	0.00	0.15
A2	0.95	1.05
b	0.15	0.27
D	7.00 BSC	
D1	5.00 BSC	
D2	3.40 REF	
D3	0.20 REF	
E	7.00 BSC	
E1	5.00 BSC	
E2	3.40 REF	
E3	---	0.30
e	0.50 BSC	
L	0.45	0.75
L2	0.25 BSC	
M	0 °	7 °



BOTTOM VIEW

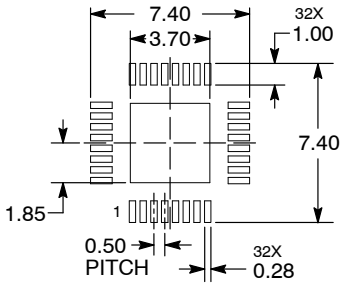
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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